501767861 12/23/2011

PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

| SUBMISSION TYPE: | NEW ASSIGNMENT |
|-----------------------|----------------|
| NATURE OF CONVEYANCE: | ASSIGNMENT |

CONVEYING PARTY DATA

| Name | Execution Date |
|------------------|----------------|
| YOSHIYASU TANAKA | 11/28/2011 |
| TAKAAKI YAMADA | 11/28/2011 |
| YUZO OSHIDA | 12/12/2011 |

RECEIVING PARTY DATA

| Name: | HITACHI SOLUTIONS, LTD. | |
|-----------------|--|--|
| Street Address: | 4-12-7, HIGASHISHINAGAWA, SHINAGAWA-KU | |
| City: | токуо | |
| State/Country: | JAPAN | |
| Postal Code: | 140-0002 | |

PROPERTY NUMBERS Total: 1

| Property Type | Number | |
|---------------------|----------|--|
| Application Number: | 13336445 | |

CORRESPONDENCE DATA

Fax Number: (202)672-5399 **Phone**: 2026725300

Email: PSHIEK@FOLEY.COM

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via

US Mail.

Correspondent Name: FOLEY & LARDNER, LLP

Address Line 1: 3000 K ST., NW
Address Line 2: SUITE 600

Address Line 4: WASHINGTON, DISTRICT OF COLUMBIA 20007

| ATTORNEY DOCKET NUMBER: | 091708-0208 | |
|-------------------------|--------------------------|--|
| NAME OF SUBMITTER: | P. SHIEK FOR W. T. ELLIS | |

Total Attachments: 1 source=assign#page1.tif

PATENT REEL: 027441 FRAME: 0672

ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi Solutions, Ltd.

a corporation organized under the laws of Japan,

located at 4-12-7,Higashishinagawa,Shinagawa-ku, Tokyo 140-0002,Japan receipt of which is hereby acknowledged I do hereby sell and assign to said. Hitachi Solutions, Ltd. its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

EMERGABLE WATERMARK SUPERIMPOSING METHOD, EMERGABLE WATERMARK SUPERIMPOSING APPARATUS, AND EMERGABLE WATERMARK SUPERIMPOSING SYSTEM

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said Hitachi Solutions, Ltd.

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-inpart, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi Solutions, Ltd.

Signed on the date(s) indicated aside our signatures:

| HAVENIOK(2) |
|---------------|
| (発明者フルネームサイン) |
| |

INVENTORIO

Date Signed

| ,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,, | | (著名目) | |
|--|------------------|------------------|---------------|
| 1)_ | Yoshiyasu TANAKA | Yoshiyasu TANAKA | Nov. 28, 2011 |
| 2)_ | Takaaki Yaunda | Takaaki YAMADA | Nov. 28. 2011 |
| 3)_ | Yuzō Oshida | Yuzo OSHIDA | Dec. 12.2011 |
| | | | |
| 5) | | | |
| | | | |
| | | | |
| 8) | | | |
| 9) | | | |
| | | | |
| | | | |

PATENT REEL: 027441 FRAME: 0673

RECORDED: 12/23/2011